Abstracts

A Computationally Efficient Method for Modeling Circuits Housed in Non-Rectangular Packages

Mathematical difficulties make a solution for parasitic impedances in packaged microstrip circuits problematic. Because of this, most present simulators model rectangular packages. In this paper, a method developed for rectangular packages is generalized to model packages with other cross sections. Reasonable accuracy is shown for a computationally efficient simulation of circuits housed in a package with trapezoidal cross section.

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